

ATTACHMENT "A"
Version with Markings to Show Changes Made

In the Claims:

Please amend Claims 1, 7, 10, and 19 as follows (Amended Claims):

1 1. A printed circuit board, comprising:
2 a plurality of conductive layers, wherein one of said plurality of conductive layers
3 is a first layer, wherein one of said plurality of conductive layers is a second layer;
4 two or more vias interconnecting two or more conductive layers of said plurality
5 of conductive layers, wherein a first of said two or more vias is part of a signal
6 path configured to carry a signal from said first layer to said second layer, wherein
7 a second of said two or more vias is part of a reference path configured to carry
8 said signal from a third layer to a fourth conductive layer, wherein said fourth
9 conductive layer returning said signal to a source; and
10 an electrical component embedded in said second of said two or more vias
11 between two conductive layers of said plurality of conductive layers, wherein said
12 electrical component has a greater diameter in a center than at ends of said
13 electrical component, wherein each end of said electrical component has a tinned
14 cap to promote solder residue adhesion to each end of said electrical component.

1 7. Canceled.

1 10. A printed circuit board, comprising:
2 a plurality of conductive layers;
3 two or more vias interconnecting two or more conductive layers of said plurality
4 of conductive layers; and

5 an electrical component embedded in a particular via between two conductive
6 layers of said plurality of conductive layers, wherein said electrical component has
7 a greater diameter in a center than at ends of said electrical component, and each
8 end of said electrical component has a tinned cap to promote solder residue
9 adhesion to each end of said electrical component.

1 19. Canceled.